

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ching-Yu Chang</td> <td>05/24/2007</td> </tr> <tr> <td>Tsai-Sheng Gau</td> <td>05/24/2007</td> </tr> <tr> <td>Burn Jeng Lin</td> <td>05/24/2007</td> </tr> </tbody> </table>		Name	Execution Date	Ching-Yu Chang	05/24/2007	Tsai-Sheng Gau	05/24/2007	Burn Jeng Lin	05/24/2007
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Ching-Yu Chang	05/24/2007								
Tsai-Sheng Gau	05/24/2007								
Burn Jeng Lin	05/24/2007								
RECEIVING PARTY DATA									
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.								
Street Address:	No. 8, Li-Hsin Road 6								
Internal Address:	Science-Based Industrial Park								
City:	Hsin-Chu								
State/Country:	TAIWAN								
Postal Code:	300-77								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11762651</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11762651				
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CORRESPONDENCE DATA									
Fax Number:	(214)200-0853								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	972-739-8660								
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ATTORNEY DOCKET NUMBER:	24061.909								
NAME OF SUBMITTER:	Liem T. Do								

CH \$40.00 11762651

Total Attachments: 2
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source=909Assignment#page2.tif

ASSIGNMENT

WHEREAS, we,

- (1) Ching-Yu Chang of No. 17, Hsinchen Road, Yuansun Village
Yilang County 264, Taiwan, R.O.C.
- (2) Tsai-Sheng Gau of No. 35, Lane 4, An-Kang Street
Hsinchu City, Taiwan, R.O.C.
- (3) Burn Jeng Lin of 153 Kuang Fu Road., Sec. 1, Lane 89, 1st FL
Hsin-Chu, Taiwan, R.O.C.

have invented certain improvements in

APPARATUS AND METHOD FOR IMMERSION LITHOGRAPHY

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
 X filed on June 13, 2007 and assigned application number 11/762,651; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ching-Yu Chang

Residence Address: No. 17, Hsinchen Road, Yuansun Village
Yilang County 264, Taiwan, R.O.C.

Dated: May 24, 2007

Ching-Yu Chang
Inventor Signature

Inventor Name: Tsai-Sheng Gau

Residence Address: No. 35, Lane 4, An-Kang Street
Hsinchu City, Taiwan, R.O.C.

Dated: 5/24, 2007

Tsai-Sheng Gau
Inventor Signature

Inventor Name: Burn Jeng Lin

Residence Address: 153 Kuang Fu Road, Sec. 1, Lane 89, 1st FL
Hsin-Chu, Taiwan, R.O.C.

Dated: May 24, 2007

Burn Jeng Lin
Inventor Signature